

NPN General Purpose Transistor

NST846BF3T5G

The NST846BF3T5G device is a spin-off of our popular SOT-23/SOT-323/SOT-563 three-leaded device. It is designed for general purpose amplifier applications and is housed in the SOT-1123 surface mount package. This device is ideal for low-power surface mount applications where board space is at a premium.

Features

- h_{FE}, 200-450
- Low $V_{CE(sat)}$, $\leq 0.25 \text{ V}$
- · Reduces Board Space
- This is a Halide–Free Device
- This is a Pb-Free Device

MAXIMUM RATINGS

Symbol	Rating	Value	Unit
V _{CEO}	Collector - Emitter Voltage	65	Vdc
V _{CBO}	Collector - Base Voltage	80	Vdc
V _{EBO}	Emitter – Base Voltage	6.0	Vdc
I _C	Collector Current - Continuous	100	mAdc

THERMAL CHARACTERISTICS

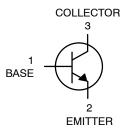
Symbol	Characteristic	Max	Unit
P _D (Note 1)	Total Device Dissipation, T _A = 25°C Derate above 25°C	290 2.3	mW mW/°C
R _{θJA} (Note 1)	Thermal Resistance, Junction-to-Ambient	432	°C/W
P _D (Note 2)	Total Device Dissipation, T _A = 25°C Derate above 25°C	347 2.8	mW mW/°C
R _{0JA} (Note 2)	Thermal Resistance, Junction-to-Ambient	360	°C/W
R _{ΨJL} (Note 2)	Thermal Resistance, Junction-to-Lead 3	143	°C/W
T _J , T _{stg}	Junction and Storage Temperature Range	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. 100 mm² 1 oz, copper traces.
- 2. 500 mm² 1 oz, copper traces.



SOT-1123 CASE 524AA STYLE 1 (Rotated 90° Clockwise



NST846BF3T5G

MARKING DIAGRAM



V = Device CodeM = Date Code

ORDERING INFORMATION

Device	Package	Shipping [†]
NST846BF3T5G	SOT-1123 (Pb-Free)	8,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

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ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Symbol	Characteristic	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
V _{(BR)CEO}	Collector – Emitter Breakdown Voltage (I _C = 10 mA)	65	-	_	V
V _{(BR)CES}	Collector – Emitter Breakdown Voltage ($I_C = 10 \mu A, V_{EB} = 0$)	80	-	_	V
V _{(BR)CBO}	Collector – Base Breakdown Voltage (I _C = 10 μA)	80	-	_	V
V _{(BR)EBO}	Emitter – Base Breakdown Voltage (I _E = 1.0 μA)	6.0	-	_	V
I _{CBO}	Collector Cutoff Current $(V_{CB} = 30 \text{ V})$ $(V_{CB} = 30 \text{ V}, T_A = 150^{\circ}\text{C})$	- -	- -	15 5.0	nA μA
ON CHARA	CTERISTICS	•	-	•	•
h _{FE}	DC Current Gain $ \begin{aligned} &(I_C=10~\mu\text{A},~V_{CE}=5.0~\text{V})\\ &(I_C=2.0~\text{mA},~V_{CE}=5.0~\text{V}) \end{aligned} $	- 200	150 290	- 450	-
V _{CE(sat)}	Collector – Emitter Saturation Voltage (I_C = 10 mA, I_B = 0.5 mA) (I_C = 100 mA, I_B = 5.0 mA)		- -	0.25 0.6	V
V _{BE(sat)}	Base – Emitter Saturation Voltage (I_C = 10 mA, I_B = 0.5 mA) (I_C = 100 mA, I_B = 5.0 mA)		0.7 0.9	- -	V
V _{BE(on)}	Base – Emitter Voltage (I_C = 2.0 mA, V_{CE} = 5.0 V) (I_C = 10 mA, V_{CE} = 5.0 V)	580 -	660 -	700 770	mV
SMALL-SI	GNAL CHARACTERISTICS				
f _T	Current – Gain – Bandwidth Product ($I_C = 10 \text{ mA}, V_{CE} = 5.0 \text{ Vdc}, f = 100 \text{ MHz}$)	100	_	-	MHz
C _{obo}	Output Capacitance (V _{CB} = 10 V, f = 1.0 MHz)	-	-	4.5	pF
C _{ibo}	Input Capacitance (V _{EB} = 0.5 V, I _C = 0 mA, f = 1.0 MHz)	_	-	10	pF
NF	Noise Figure (I _C = 0.2 mA, V _{CE} = 5.0 Vdc, R _S = 2.0 k Ω , f = 1.0 kHz, BW = 200 Hz)	-	-	10	dB

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

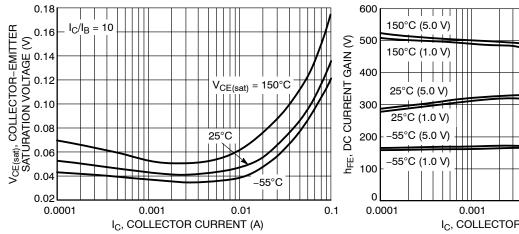


Figure 1. Collector Emitter Saturation Voltage vs. **Collector Current**

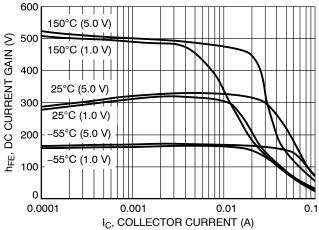


Figure 2. DC Current Gain vs. Collector Current

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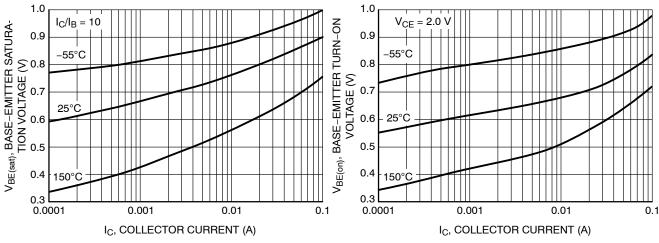


Figure 3. Base Emitter Saturation Voltage vs. Collector Current

Figure 4. Base Emitter Turn-On Voltage vs.
Collector Current

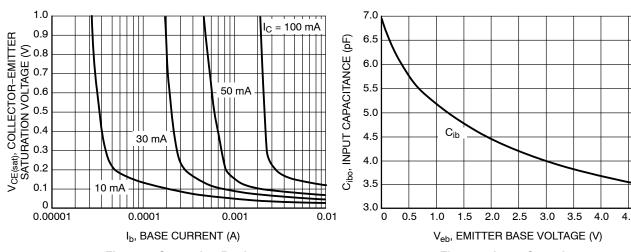


Figure 5. Saturation Region

Figure 6. Input Capacitance

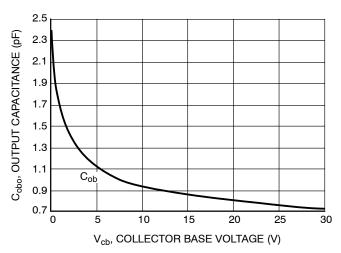


Figure 7. Output Capacitance



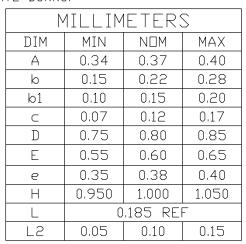


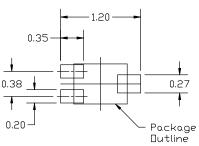
SOT-1123 0.80x0.60x0.37, 0.35P CASE 524AA ISSUE D

DATE 18 JAN 2024

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
- 2. CONTROLLING DIMENSION: MILLIMETERS.
- 3, MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH.
 MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS
 OF BASE MATERIAL.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

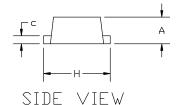




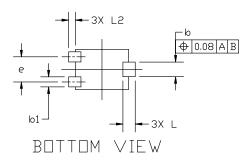
RECOMMENDED MOUNTING FOOTPRINT

*For additional information on our Pb-Free strategy and soldering details, please download th e □N Semiconductor Soldering and Mounting Techniques Reference manual, S□LDERRM/D.

I	—A B
	E



THP VIFW



GENERIC MARKING DIAGRAM*



X = Specific Device Code

M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

STYLE 1:
PIN 1. BASE
EMITTER
3 COLLECTOR

STYLE 2: PIN 1. ANODE 2. N/C 3. CATHODE

STYLE 3: PIN 1. ANODE 2. ANODE 3. CATHODE

STYLE 4: PIN 1. CATHODE 2. CATHODE 3. ANODE STYLE 5: PIN 1. GATE 2. SOURCE

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DESCRIPTION:	SOT-1123 0.80x0.60x0.37, 0.35P		PAGE 1 OF 1	

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